

5. (Amended) A method of manufacturing a semiconductor device comprising the steps of:

Q2 abrasing to a mirror finish a surface of a semiconductor substrate opposite to a surface thereof having an external connection electrode; and  
applying resin on said surface abraded.

Please add the following claims:

--17. (New) a semiconductor device comprising:

a semiconductor substrate having a first surface with an external connection electrode;

a second surface which is a mirror finished surface opposite to said first surface; and

Q3 a back surface reinforcement member on said second surface which is mirror finished.

18. (New) a method of manufacturing a semiconductor device comprising the steps of:

providing a mirror finished surface on a first surface of a semiconductor substrate;

providing an external connection electrode on a second surface which is opposite to the first surface; and

applying resin on the mirror finished surface.--